

FOR : BE SEMICONDUCTOR INDUSTRIES N.V.  
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## **PRESS RELEASE**

### **BE Semiconductor Industries Announces 2009 Third Quarter Results Release and Investor/Analyst Conference Call and Webcast Date**

Duiven, the Netherlands, October 22, 2009, BE Semiconductor Industries N.V. ("Besicon") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, will release results for the third quarter ended September 30, 2009, on Thursday, October 29, 2009 at 8.00 a.m. Continental European Time (2.00 a.m. New York time).

Besicon will host an investor/analyst conference call and audio webcast (log on via [www.besi.com](http://www.besi.com)) to discuss its results for the third quarter ended September 30, 2009, on Thursday, October 29, 2009 at 4.00 p.m. CET (10.00 a.m. New York time). The teleconference dial-in number is (31) 70 304 3381. The audio webcast will remain available on [www.besi.com](http://www.besi.com).

#### **About BE Semiconductor Industries N.V.**

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, wire bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European, Asian, Korean and Japanese semiconductor manufacturers and subcontractors which utilize its products for both array connect and conventional leadframe manufacturing processes.

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